

4.7mm HOUSING FOR LED LAMP WITH WIRE



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: WP1533AA/ID14V-W152

High Efficiency Red

Features

- Outstanding material efficiency.
- Reliable and rugged.
- Low current capability.
- Housing UL rating: 94V-0.
- Housing material: type 66 nylon.
- 14V internal resistor.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions

Fig.1:

ANODE LEAD :RED INSULATION LEAD ,24 AWG ,UL#1007,Ø1.45mm, TINNED OVERCOATED WIRE , STRIP 12.7mm.

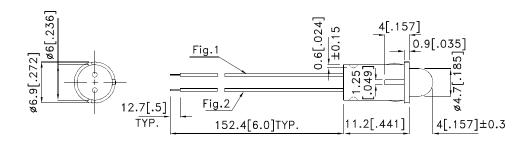
Fig. 2 :

CATHODE LEAD :BLACK INSULATION LEAD ,24 AWG,UL#1007 ,ø1.45mm,

TINNED OVERCOATED WIRE, STRIP 12.7mm.

Fig.3 :

STAKING TO FIX THE HOLDER AND LED .



Remark

Recommended panel mount hole diameter $\phi = 6.30 \text{-} 6.35 \text{mm};$ panel thickness 1.0 mm.

Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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 ERP: 1102009531

Selection Guide

| Part No. | Dice | Lens Type | lv (mcd) [2] V= 14V | | Viewing Angle [1] |
|---------------------|------------------------------------|--------------|------------------------|------|----------------------|
| | | 2,1 | Min. | Тур. | 201/2 |
| WP1533AA/ID14V-W152 | High Efficiency Red (GaAsP/GaP) | Red Diffused | 15 | 50 | 60° |
| | I TIGHT EILICIENCY REG (GAASP/GAP) | Red Dillused | *8 *25 | *25 | |

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%.

 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|---------------------|------|------|-------|-----------------|
| λpeak | Peak Wavelength | High Efficiency Red | 627 | | nm | VF=14V |
| λD [1] | Dominant Wavelength | High Efficiency Red | 617 | | nm | VF=14V |
| Δλ1/2 | Spectral Line Half-width | High Efficiency Red | 45 | | nm | VF=14V |
| lF | Forward Current | High Efficiency Red | 10.5 | 13.5 | mA | VF=14V |
| lR | Reverse Current | High Efficiency Red | | 10 | uA | VR = 5V |

- 1.Wavelength: +/-1nm.
- 2. Wavelength value is traceable to the CIE127-2007 compliant national standards.

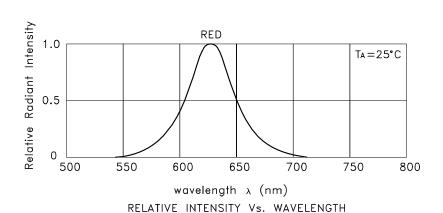
Absolute Maximum Ratings at TA=25°C

| Parameter | High Efficiency Red | Units | |
|-----------------------------|---------------------|-------|--|
| Power dissipation | 160 | mW | |
| Forward Voltage | 16 | V | |
| Reverse Voltage | 5 | V | |
| Operating Temperature | -40°C To +70°C | | |
| Storage Temperature | -40°C To +85°C | | |
| Lead Solder Temperature [1] | 260°C For 3 Seconds | | |
| Lead Solder Temperature [2] | 260°C For 5 Seconds | | |

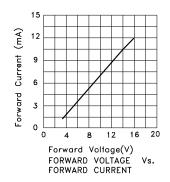
- 2mm below package base.
 5mm below package base.

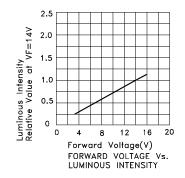
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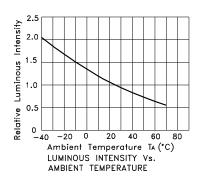
High Efficiency Red

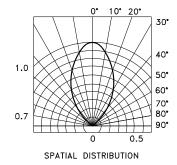


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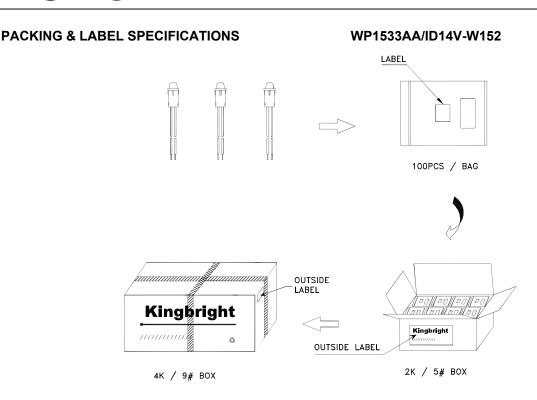






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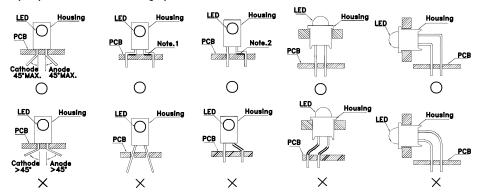
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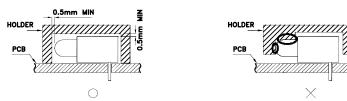
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PRECAUTIONS

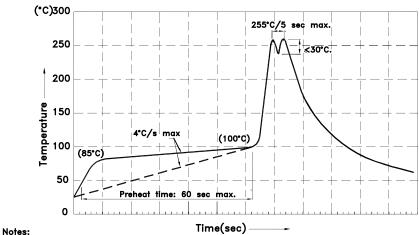
 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



- " \bigcirc " Correct mounting method "imes" Incorrect mounting method
- 2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

2.Peak wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

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AMEYA360 Components Supply Platform

Authorized Distribution Brand:

























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